

**REMARKS**

By this amendment, the Applicant cancels claims 1 and 7. New claims 20-55 are presented for examination. Therefore, on entering this amendment, 2-6 and 8-55 are all the claims pending in the application.

Claims 1, 2, 15 and 17-19 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Jinno et al. (JP 5-342918) in view of Tanaka (5,455,383).

Claims 3-5 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Jinno et al. (JP 5-342918) in view of Tanaka (5,455,383) as applied to claim 1 and further in view of Shibata.

Claim 6 has been rejected under 35 U.S.C. § 103(a) as being unpatentable over Jinno et al. (JP 5-342918) in view of Tanaka (5,455,383) and further in view of Lin.

Claims 7-10 and 14 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Jinno et al. (JP 5-342918) in view of Tanaka (5,455,383) and further in view of JP10-251606.

Claims 11- 13 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Jinno et al. (JP 5-342918) in view of Tanaka (5,455,383) and further in view of Yoshikawa.

The Applicants traverse the rejections and request reconsideration

The Applicants respectfully delete claims 1 and 7 and rewrite claims 2, 3, 5 and 6.

According to non-limiting illustrative embodiments of the present invention, by mixing phosphoric acid methacrylate and melamine-based resin with the resin (base resin) enhancement of adhesion to a resin such as polyimide or polyethylene terephthalate used in the substrate (21) and protective insulating layer (23) of the cable body (20) and the substrate (31) of the shielding member (30) is realized. Further, adhesion to metal thin film such as a copper thin film used as

the shielding conductive layer (32) is also realized. Therefore, the connection reliability of the shield flat cable (10) can be improved significantly.

Jinno, Tanaka and Yoshikawa neither disclose nor suggest "mixing further the phosphoric acid methacrylate and melamine based resin with the resin (base resin)" as set forth in the amended claims 2, 3, 5 and 6. A skilled artisan would not have been able to make the present invention based on the combined teachings of Jinno/Tanaka/Yoshikawa.

Though the examiner asserts that JP10-251606 discloses the use of "a phosphoric acid methacrylate and melamine-based resin," the resin disclosed by JP10-251606 is merely a "resin comprising mixture of the thermoplastic resin and a thermosetting plastic with a predetermined ratio as a base resin". The resin comprising such a mixture is quite different from the ones according to the present invention.

In other words, JP10-251606 aims to realize a conductive adhesive having a good performance in both of adhesiveness and reworkability. This was done to overcome the difficulties where use of conductive adhesive comprising a "thermosetting resin" as a base resin resulted in a high adhesiveness but an inferior reworkability. On the other hand, use of a "thermoplastic resin" as a base resin resulting in improved reworkability but an inferior adhesiveness. To overcome some of these difficulties, JP10-251606 is aimed at realizing good performance of the conductive adhesive in both of adhesiveness and reworkability "by mixing the thermoplastic resin and the thermosetting resin in a predetermined ratio and obtaining the resin comprising the mixed resin as the base resin".

In contrast with JP10-251606, present invention according to amended claims 2, 3, 5 and 6 aims to improve further the adhesion to a resin such as polyimide or polyethylene terephthalate

and to a metal thin film such as a copper thin film by not only using the "thermosetting resin" having a high adhesiveness as the base resin, but also by further adding a "phosphoric acid methacrylate and melamine base resin" to the resin as set forth by the original claims 2-6. Thus, the problem to be solved by the present invention, structure and resulting advantages are essentially distinctive from those of JP10-251606.

Further, JP10-251606, as an example of a "thermosetting resin", only "melamine based resin" is suggested and the "phosphoric acid methacrylate" is neither disclosed nor suggested.

The "melamine based resin" as disclosed in JP10-251606 is exemplified merely as an example of a "thermosetting resin to be mixed with a thermoplastic resin." But, such a mixing is not made with an aim of improvement of adhesiveness of the electrical conductive adhesive of the resin comprising the "thermosetting resin" as a base resin as disclosed by the present invention. Further, JP10-251606 neither discloses nor suggests the feature of the present invention where phosphoric acid methacrylate and melamine-based resin are mixed with the resin (base resin).

Thus, even if the teachings of JP10-251606 were to be applied to Tanaka or other cited references, the present invention is not suggested by the combination.

Claims 8-19 have been amended to depend on claim 2, and are believed to be allowable for the reasons discussed above.

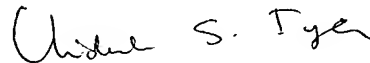
New claims 20-55, depending from claim 3, 5 and 6 are presented herein for examination. The above arguments are believed to be equally applicable for these claims.

**CONCLUSION**

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

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Respectfully submitted,



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